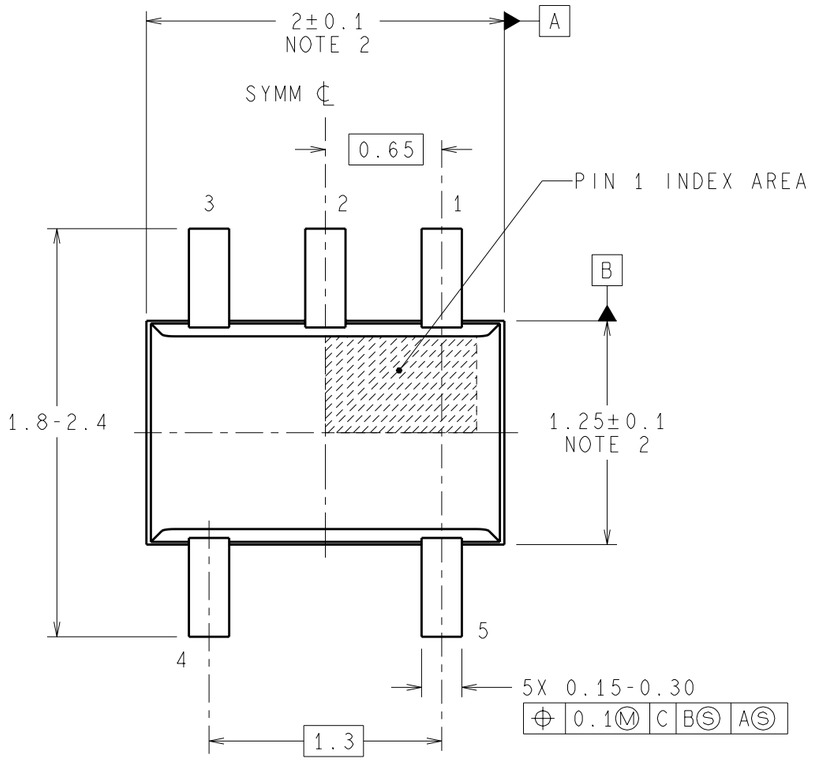
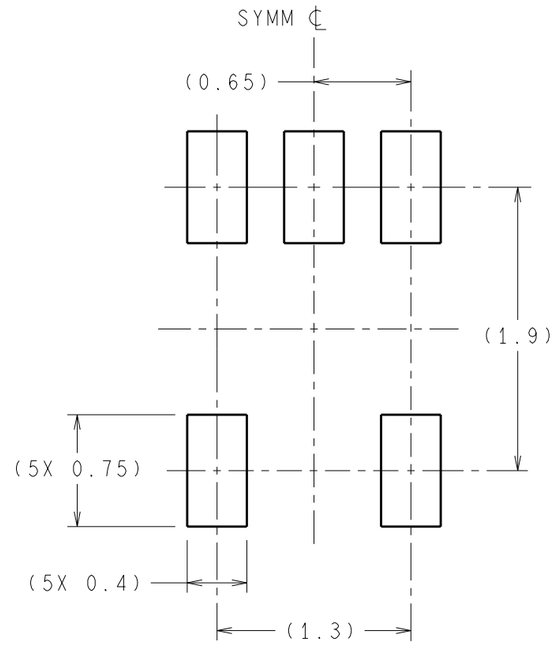
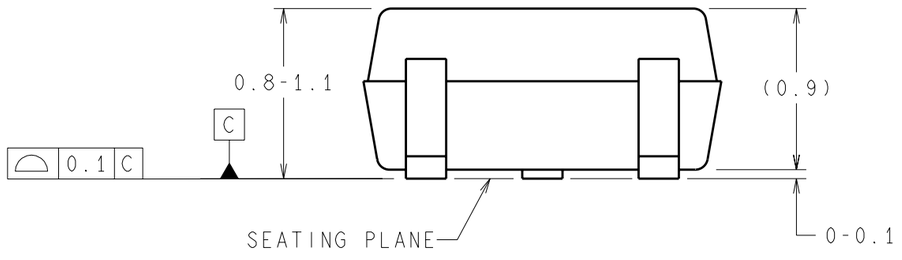
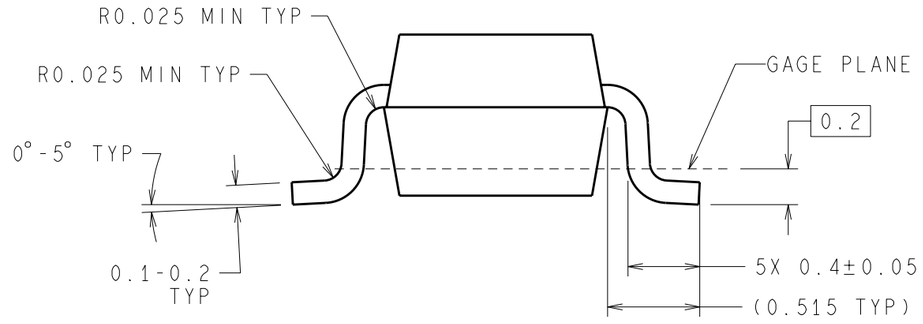
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11819	09/16/1997	KML/MS/AL
B	LEADSPREAD DIM 1.8-2.4 WAS 2.1±0.1; LAND PATTERN DIST. 1.9 WAS 1.65.)	12055	09/11/1998	NOR/MS/AL
C	UPDATE DWG TO CURRENT STD'S; REVISE NOTE 1; & TITLE; CHANGE TO B SIZE FORMAT.	1015	04/29/2003	MS/RW
D	ADD PIN 1 INDEX AREA; UPDATE TITLE PER STDS	2318	06/07/2007	TL/RW





LAND PATTERN RECOMMENDATION





NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION DOES NOT INCLUDE MOLD FLASH.

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFENRENCE ONLY

APPROVALS	DATE
DRAWN K M LOO	09/16/1997
DFTG. CHK. MARTA SUCHY	06/07/2007
ENGR. CHK. RANDALL WALBERG	06/07/2007

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

MOLDED SC-70, 2x1.25x0.9mm, 5 LEAD, 0.65mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-MAA05A	D

FORMERLY: N/A